

Diode

Silicon Carbide Schottky Diode

IDH02G120C5

5th Generation CoolSiC™ 1200 V SiC Schottky Diode

Final Datasheet

Rev. 2.2 2021-03-01

Industrial Power Control



CoolSiC[™] SiC Schottky Diode

Features:

- Revolutionary semiconductor material Silicon Carbide
- No reverse recovery current / No forward recovery
- Temperature independent switching behavior
- Low forward voltage even at high operating temperature
- Tight forward voltage distribution
- Excellent thermal performance
- Extended surge current capability
- Specified dv/dt ruggedness
- Qualified according to JEDEC¹⁾ for target applications
- Pb-free lead plating; RoHS compliant

Benefits

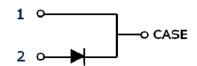
- System efficiency improvement over Si diodes
- Enabling higher frequency / increased power density solutions
- System size / cost savings due to reduced heatsink requirements and smaller magnetics
- Reduced EMI
- Highest efficiency across the entire load range
- Robust diode operation during surge events
- High reliability
- RelatedLinks: www.infineon.com/sic

Applications

- Solar inverters
- Uninterruptable power supplies
- Motor drives
- Power Factor Correction

Package pin definitions

- Pin 1 and backside cathode
- Pin 2 anode













Key Performance and Package Parameters

Туре	$V_{ m DC}$	I F	Q _C	$ all_{ extsf{j,max}}$	Marking	Package
IDH02G120C5	1200V	2A	14nC	175°C	D0212C5	PG-TO220-2-1

1) J-STD20 and JESD22





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Maximum ratings

Parameter	Symbol	Value	Unit	
Repetitive peak reverse voltage	V _{RRM}	1200	V	
Continues forward current for $R_{th(j-c,max)}$ $T_C = 168^{\circ}C$, D=1 $T_C = 135^{\circ}C$, D=1 $T_C = 25^{\circ}C$, D=1	I F	2 5.7 11.8	А	
Surge non-repetitive forward current, sine halfwave $T_C=25$ °C, $t_p=10$ ms $T_C=150$ °C, $t_p=10$ ms	<i>I</i> F,SM	37 31	А	
Non-repetitive peak forward current $T_{\rm C} = 25^{\circ}{\rm C}$, $t_{\rm p}=10~{\rm \mu s}$	I _{F,max}	344	А	
i^2 t value $T_C = 25^{\circ}\text{C}, \ t_p = 10 \text{ ms}$ $T_C = 150^{\circ}\text{C}, \ t_p = 10 \text{ ms}$	∫ i²dt	7 4.9	A²s	
Diode dv/dt ruggedness V_R =0960V	d <i>v</i> /d <i>t</i>	150	V/ns	
Power dissipation $T_C = 25$ °C	P _{tot}	75	W	
Operating and storage temperature	$T_{\rm j}$; $T_{ m stg}$	-55175	°C	
Soldering temperature, wavesoldering only allowed at leads, 1.6mm (0.063 in.) from case for 10 s	Tsold	260	°C	
Mounting torque M3 and M4 screws	М	0.7	Nm	

Thermal Resistances

Parameter	Cumbal	Conditions	Value			l lmit
rarameter	Symbol		min.	typ.	max.	Unit
Characteristic						
Diode thermal resistance, junction – case	R _{th(j-c)}		-	1.54	2	K/W
Thermal resistance, junction – ambient	R _{th(j-a)}	leaded	-	-	62	K/W



Electrical Characterics

Static Characteristics, at T_j=25°C, unless otherwise specified

Parameter	Symbol	Conditions min.		Value	Unit	
raiailletei			min.	typ.	max.	Oilit
Static Characteristic						
DC blocking voltage	V _{DC}	<i>T</i> _j = 25°C	1200	-	-	V
Diode forward voltage	V _F	<i>I</i> _F = 2A, <i>T</i> _j =25°C	-	1.4	1.65	V
	VF	<i>I</i> _F = 2A, <i>T</i> _j =150°C	-	1.7	2.3	
Reverse current	l ₀	V _R =1200V, T _j =25°C		1.2	18	
	/ R	<i>V</i> _R =1200V, <i>T</i> _j =150°C		6	90	μΑ

Dynamic Characteristics, at T_j=25°C, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
r ai ailietei	Syllibol		min.	typ.	max.	01111
Dynamic Characteristics						
Total capacitive charge		V _R =800V, T _j =150°C				
	Qc	$Q_C = \int_C^{V_R} C(V) dV$	-	14	-	nC
		0				
		V _R =1 V, <i>f</i> =1 MHz	-	182	-	
Total Capacitance	С	V _R =400 V, <i>f</i> =1 MHz	-	13	-	pF
		V _R =800 V, <i>f</i> =1 MHz	-	10	-	



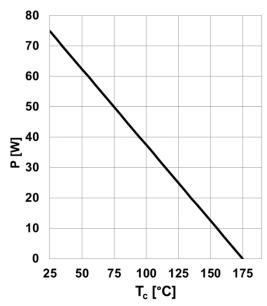


Figure 1. Power dissipation as a function of case temperature, $P_{tot} = f(T_C)$, $R_{th(j-c),max}$

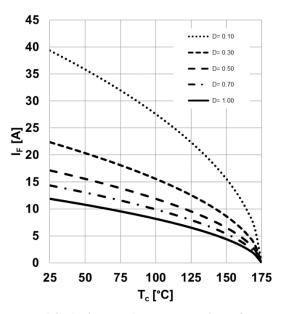


Figure 2. **Diode forward current as function of temperature,** T_j ≤175°C, $R_{\text{th(j-c),max}}$, parameter D=duty cycle, V_{th} , R_{diff} @ T_j =175°C

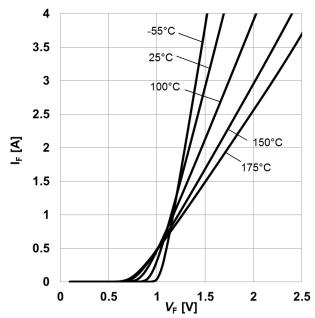


Figure 3. **Typical forward characteristics,** $I_F = f(V_F)$, $t_p = 10 \mu s$, parameter: T_j

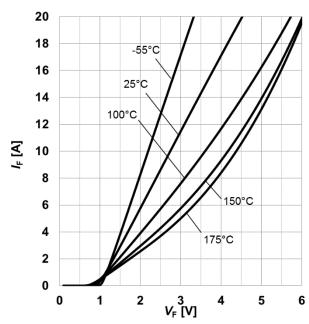


Figure 4. Typical forward characteristics in surge current, $I_F=f(V_F)$, $t_p=10 \mu s$, parameter: T_j



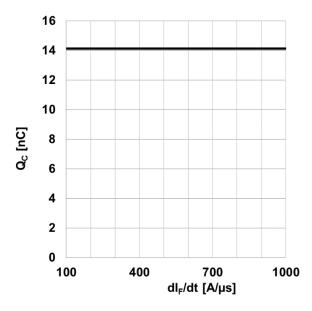


Figure 5. **Typical capacitive charge as function of current slope**¹, $Q_C = f(dI_F/dt)$, $T_j = 150^{\circ}C$ 1) Only capacitive charge, guaranteed by design.

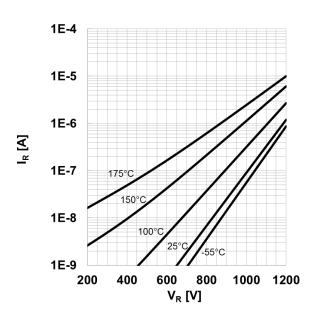


Figure 6. Typical reverse current as function of reverse voltage, $I_R=f(V_R)$, parameter: T_j

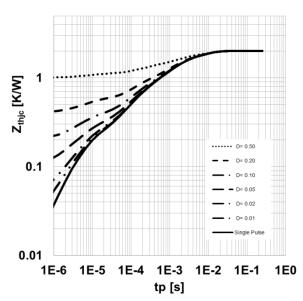


Figure 7. **Max. transient thermal impedance,** $Z_{\text{th,jc}} = f(t_P)$, parameter: $D = t_P/T$

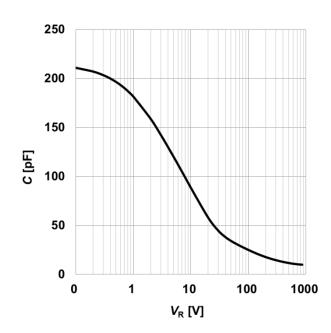


Figure 8. **Typical capacitance as function of** reverse voltage, $C=f(V_R)$; $T_j=25^{\circ}C$; f=1 MHz



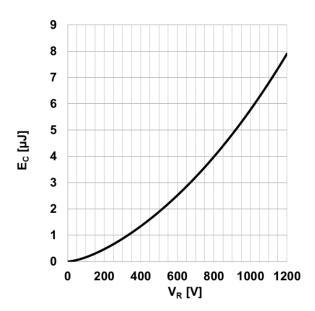
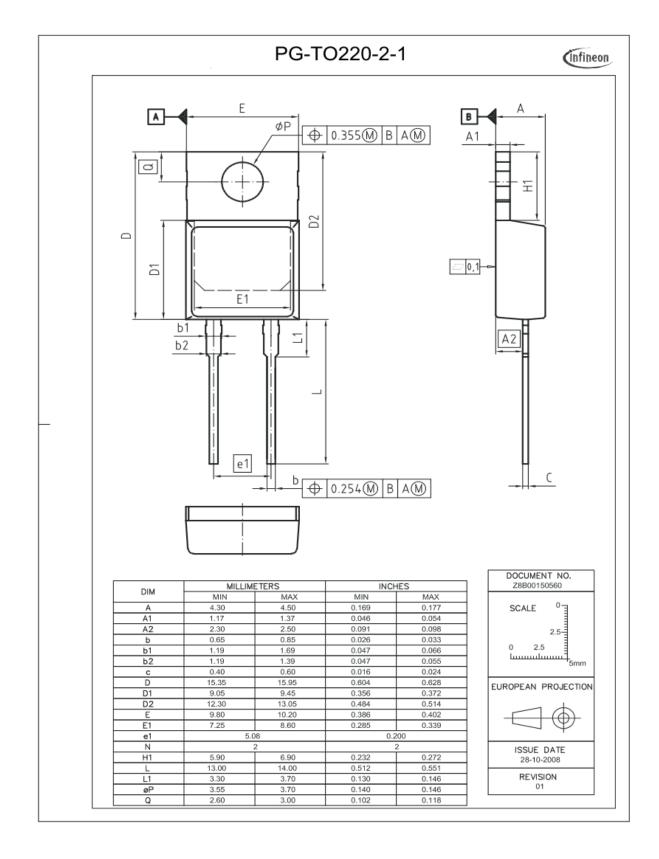


Figure 9. Typical capacitively stored energy as function of reverse voltage,

$$E_C = \int_0^{V_R} C(V)VdV$$









Revision History

IDH02G120C5

Revision:2021-03-01, Rev. 2.2

Previous Revision:

Revision	Date	Subjects (major changes since last version)			
2.0	2015-07-22	Final data sheet			
2.1	2017-07-21	Editorial change			
2.2	2021-03-01	Increased dv/dt ruggedness			

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